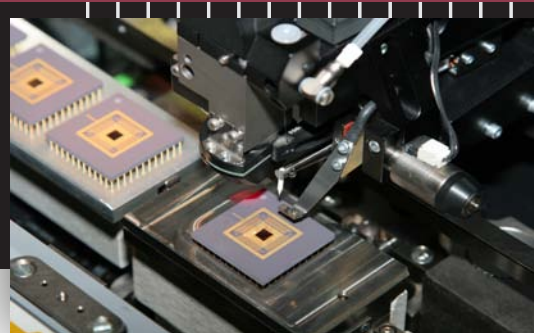


Ceramic Packaging and Assembly



Advantages:

- High Temperature, High Rel. Capability
- Wide Range of Package and Lid Configurations
- Turnaround in 24 Hours or Less
- ITAR Registered
- ISO 9001:2000 Certified

Quik-Pak's Ceramic Packages and assembly enable faster design verification and quicker time to market for your new devices. When ceramic packages are the right vehicle for your prototype devices, Quik-Pak can provide a full turnkey solution. We will either use your packages or procure the packages from industry-leading ceramic suppliers and assemble your devices to your specifications.

Assembly Options Include:

- Die attach: filled epoxies, silver-glass, silver-filled cyanate ester and gold eutectic
- Non-destructive bond pull for Class S standard
- Solder, glass or epoxy lid seal
- Glop-top available
- Marking: Mil standard permanency

Flexibility

Quik-Pak can procure and assemble virtually every type of ceramic package available - all in the most common sizes and configurations and open-tooled designs. No matter how large or small the requirement, we offer a reliable way to shorten lead times and reduce cost of materials. Packages are available with a variety of lids including taped-on, ceramic, combo, glass and hermetically sealed.

Speed

When you need a full turn-key solution, Quik-Pak can do it all - from wafer dicing and backgrinding, package procurement and preparation to die attach, wire bonding, encapsulation, remolding and marking. We deliver production-quality prototype parts for internal testing or customers samples to meet your deadline.

Quik-Pak

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